SLD5S Series Surface Mount

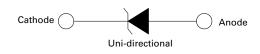
Agency Approvals

Agency	Agency File Number
91	E230531

Maximum Ratings and Thermal Characteristics $(T_A=25^{\circ}C \text{ unless otherwise noted})$

Parameter	Symbol	Value	Unit
Peak Pulse Power Dissipation 1. 10ms/150ms test waveform	P _{PPM}	1200	W
2. 10µs/1000µs test waveform	FFIVI	3600	W
Power dissipation on infinite heatsink at T _c = 25 °C	P _D	5.0	W
Maximum Instantaneous Forward Voltage at 100A for Unidirectional only	$V_{\rm F}$	1.8	V
Peak forward surge current 8.3m single half sine-wave	I _{FSM}	500	А
Operating Junction and Storage Temperature Range	T _J , T _{stg}	-55 to 150	°C
Typical Thermal Resistance Junction to case	$R_{_{ extsf{ heta}JC}}$	1.3	°C/W
Typical Thermal Resistance Junction to Ambient	$R_{_{\theta JA}}$	14	°C/W

Functional Diagram



🚘 AUTOMOTIVE GRADE

Description

The SLD5S unidirectional TVS Diode series is housed in a SMTO-263 package with lead modifications. It is designed to protect sensitive electronics against ESD, EFT, 10/1000 surge events and inductive load switching voltage transient events for severe Automotive Load Dump applications.

Features & Benefits

- AEC-Q101 qualified with automotive grade (PPAP capable)
- SMTO-263 package, and foot print is compatible to industrial popular DO-218AB package
- Meet ISO7637-2 5a/5b protection, ISO16750 and JASO D-001 load dump test (refer to APP note for details)
- VBR @TJ= VBR@25°C x (1+αT x (TJ - 25))(αT:Temperature Coefficient, typical value is 0.1%
- Glass passivated chip junction in modified TO-263 package
- ESD protection of data lines in accordance with IEC 61000-4-2, 30kV(Air), 30kV (Contact)
- EFT protection of data lines in accordance with IEC 61000-4-4
- Fast response time: typically less than 1.0ps from 0 Volts to VBR min

Applications

Designed to protect sensitive electronics from:

- Inductive Load Switching
- Alternator Load Dump



- Low incremental surge resistance
- UL Recognized compound meeting flammability rating V-0
- Meets MSL level 1, per J-STD-020, High temperature reflow soldering guaranteed: 260°C/10sec at terminals
- For surface mounted applications to optimize board space
- Low profile package
- Matte tin lead–free plated
- Halogen free and RoHS compliant
- Pb-free E3 means 2nd level interconnect is Pb-free and the terminal finish material is tin (Sn) (IPC/JEDEC J-STD-609A.01)



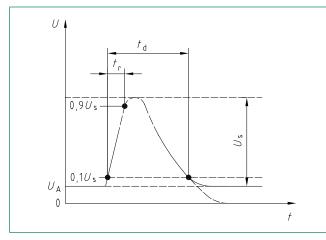
					A				
Part Number (Uni)	Voltage (1	kdown 9 V _{BR} @ I _T V)	Test Current I _T (mA)	Reverse Stand off Voltage V _R (Volts)	Maximum Reverse Leakage I _R @ V _R	T _J =150°C Max. Reverse Leakage I _R @ V _R	Maximum Peak Pulse Surge Current I _{pp}	Maximum Clamping Voltage V _c @ I _{pp}	Agency Approval
	MIN	MAX	(IIIA)	(10103)	(µA)	(µA)	(A)	(V)	
SLD5S14A	15.6	17.2	5.0	14	10	50	155	23.2	Х
SLD5S15A	16.7	18.5	5.0	15	10	50	148	24.4	Х
SLD5S16A	17.8	19.7	5.0	16	2.0	50	138	26.0	Х
SLD5S17A	18.9	20.9	5.0	17	2.0	50	130	27.6	Х
SLD5S18A	20.0	22.1	5.0	18	2.0	50	123	29.2	Х
SLD5S20A	22.2	24.5	5.0	20	2.0	50	111	32.4	Х
SLD5S22A	24.4	26.9	5.0	22	2.0	50	101	35.5	Х
SLD5S24A	26.7	29.5	5.0	24	2.0	50	93	38.9	Х
SLD5S26A	28.9	31.9	5.0	26	2.0	50	86	42.1	Х
SLD5S27A	29.9	33.1	5.0	27	2.0	50	83	43.6	Х
SLD5S28A	31.1	34.4	5.0	28	2.0	50	79	45.4	Х
SLD5S30A	33.3	36.8	5.0	30	2.0	50	74	48.4	Х
SLD5S33A	36.7	40.6	5.0	33	2.0	50	68	53.3	Х
SLD5S36A	40.0	44.2	5.0	36	2.0	50	62	58.1	Х
SLD5S40A	44.4	49.1	5.0	40	2.0	50	56	64.5	Х

Electrical Characteristics ($T_A = 25^{\circ}C$ unless otherwise noted)

Notes:

1. V_{ini} measured after I₁ applied for 300µs, I₁= square wave pulse or equivalent. 2. Surge current waveform per 10µs/1000µs exponential wave and derated per Fig. 2

3. All terms and symbols are consistent with ANSI/IEEE C62.35.

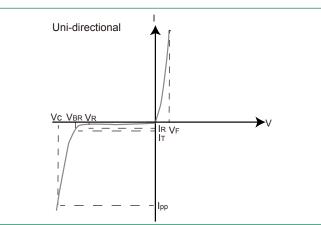


Load Dump Test Wave Form

Parameter	12V system	24V system	
U _s	65v to 87V	123V to 174V	
R	0.5Ω to 4Ω	1Ω to 8Ω	
t _d	40 ms to 400 ms	100 ms to 350 ms	
t _r	(10 ⁰ ₋₅)ms		

Note: LF use td=400ms for 12V system test; td=350ms for 24V system





I-V Curve Characteristics

P_{PPM} Peak Pulse Power Dissipation – Max power dissipation

- $\mathbf{V}_{_{\!R}}$ **Stand-off Voltage** Maximum voltage that can be applied to the TVS without operation
- V_{ss} Breakdown Voltage Maximum voltage that flows though the TVS at a specified test current (I₁)
- V_c Clamping Voltage Peak voltage measured across the TVS at a specified I_{PPM} (peak impulse current)
- ${\bf I}_{_{\! R}}$ Reverse Leakage Current -- Current measured at $V_{_{\! R}}$
- V, Forward Voltage Drop for Uni-directional

Ratings and Characteristic Curves (T_A=25°C unless otherwise noted)

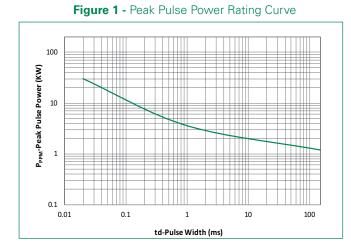


Figure 3 - Typical Transient Thermal Impedance

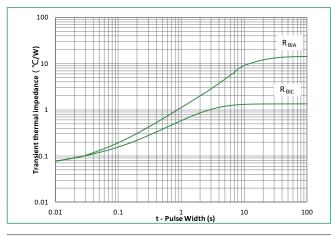


Figure 2 - Peak Pulse Power Derating Curve

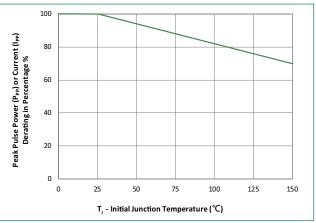
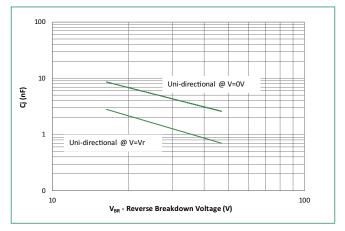


Figure 4 - Typical Junction Capacitance





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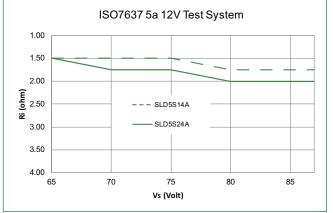
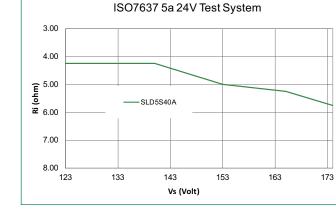


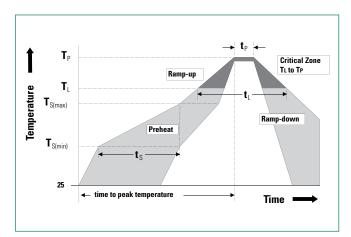
Figure 5 - Typical SOA Chart



Note: SOA (Safe Operation Area) refer to the area which below the curve line and refer to APP note for details.

Reflow Condition		Lead-free assembly	
	- Temperature Min (T _{s(min)})	150°C	
Pre Heat	- Temperature Max (T _{s(max)})	200°C	
	- Time (min to max) (t _s)	60 - 120 secs	
Average ram peak	p up rate (Liquidus Temp (T_L) to	3°C/second max	
$T_{S(max)}$ to T_{L} - Ramp-up Rate		3°C/second max	
Reflow	- Temperature (T _L) (Liquidus)	217°C	
	- Time (min to max) (t _L)	60 – 150 seconds	
Peak Temper	ature (T _P)	260 ^{+0/-5} °C	
Time within	5°C of actual peak Temperature (t _p)	30 seconds max	
Ramp-down	Rate	6°C/second max	
Time 25°C to peak Temperature (T _P)		8 minutes max.	
Do not exceed		260°C	

Soldering Parameters

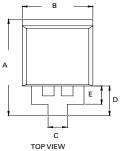


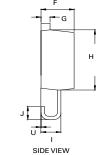
Physical Specifications

Terminal Finish	100% Matte Tin-plated
Body Material	UL Recognized compound meeting flammability classification 94V-0
Lead Material	Copper Alloy

Environmental Specifications

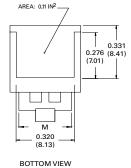
High Temp. Storage	JESD22-A103
HTRB	JESD22-A108
Temperature Cycling	JESD22-A104
MSL	JEDEC-J-STD-020, LEVEL 1
H3TRB	JESD22-A101
RSH	JESD22-A111

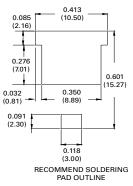




Dimensions

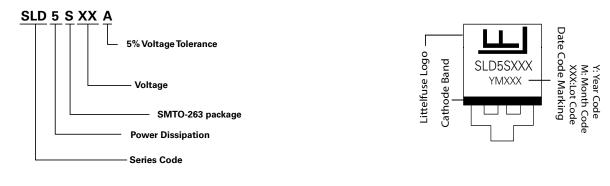
Dimensions	Incl	hes	Millimeters		
Dimensions	Min	Max	Min	Max	
А	0.568	0.600	14.44	15.24	
В	0.380	0.420	9.65	10.67	
С	0.098	0.114	2.50	2.90	
D	0.169	0.189	4.30	4.80	
E	0.102	0.118	2.60	3.00	
F	0.178	0.188	4.52	4.78	
G	0.045	0.060	1.14	1.52	
Н	0.360	0.370	9.14	9.40	
I.	0.106	0.122	2.69	3.09	
J	0.069	0.089	1.75	2.25	
М	0.284	0.300	7.22	7.62	
U	0	0.010	0	0.25	





Part Numbering System



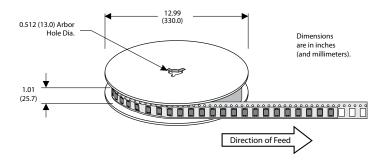


Packaging

Part Number	Component Package	Quantity	Packaging Option
SLD5SxxA	SMTO-263	500	Embossed Carrier

SMTO-263 Embossed Carrier Reel Pack (RP) Specifications Meets all EIA-481-2 Standards

0.63 → 0.157 (16.0) → 0.059 (1.5) DIA (1.5) DIA (21.0) → 0.827 * (21.0) → 0.827 * (21.0) → 0.827 * (21.0) → 0.059 → 0.059 (1.5) → 0.059 → 0.0



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